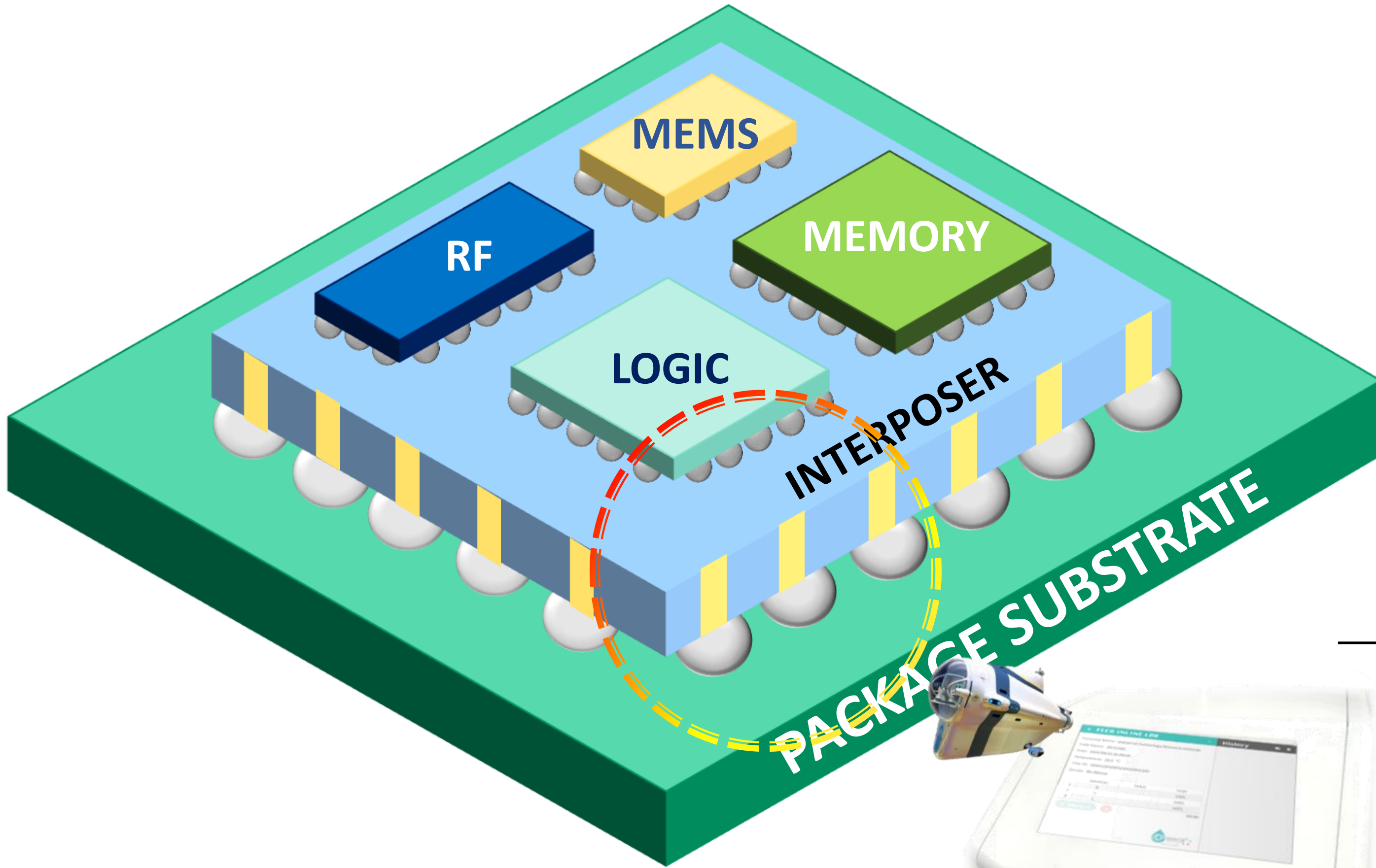
3D Electroplating Chemical Additive Real-Time Detection Technology



Using Fast Electrochemical Capturing Analysis (FECA) technology, all additives and metals in 3D packaging electroplating solution can be analyzed within 5 minutes

System	Components
Copper Electroplating System (RDL, TSV)	① Brightener ② Suppressor ③ Leveler ④ Copper Ions
Tin-Silver Electroplating System (Micro Bump):	① Accelerator ② Methanesulfonic Acid ③ Silver Complex Agent ④ Divalent Tin

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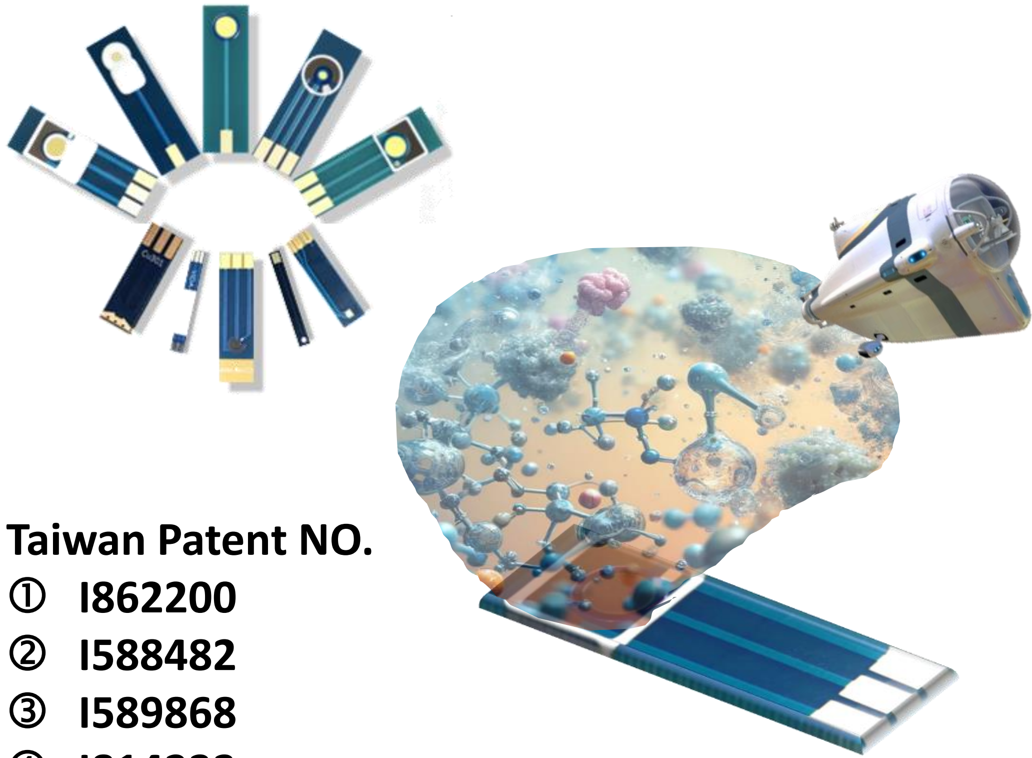
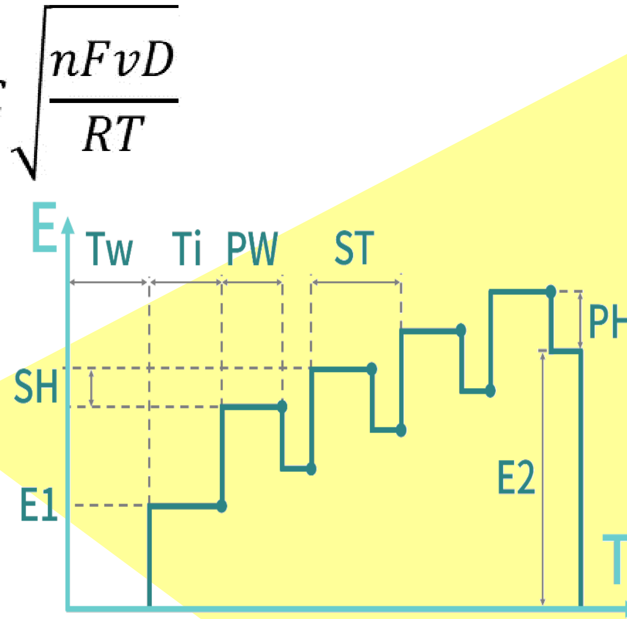
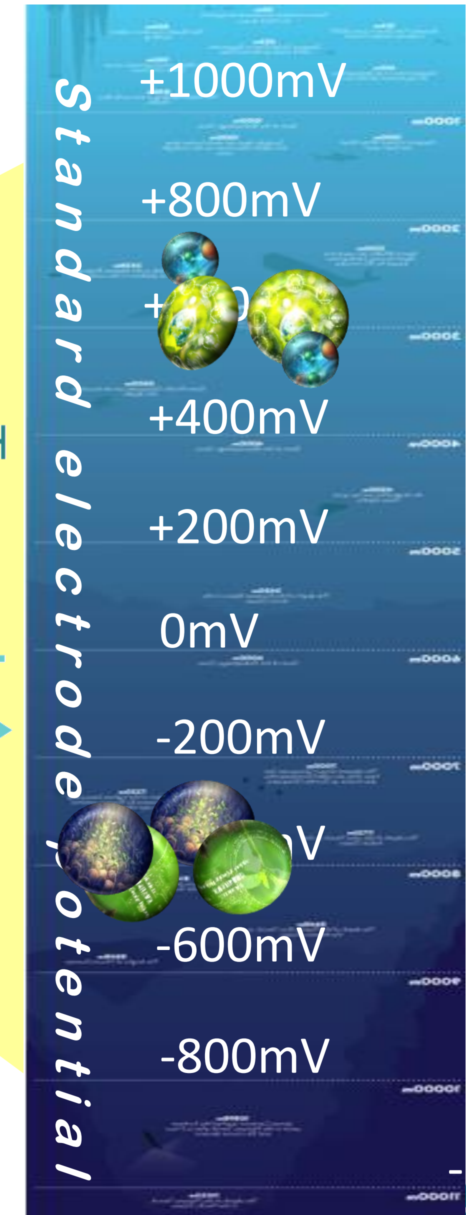
Fast Electrochemical Capturing Analysis(FECA)

Nernst equation: **O+ne^{-}↔R**

Randles-Sevcik Equation: $i_p = 0.4463\, nFAC \sqrt{\frac{nFvD}{RT}}$







Taiwan Patent NO.

① I862200
② I588482
③ I589868
④ I814233
⑤ I589870

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